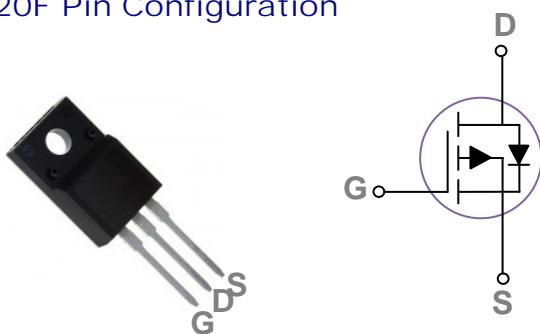


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO220F Pin Configuration



BVDSS	RDS(ON)	ID
-60V	48mΩ	-15A

### Features

- -60V, -15A, RDS(ON) = 48mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	-15	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	-9.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-60	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	51	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	-32	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	19	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.15	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	6.7	$^\circ\text{C}/\text{W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.05	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-8\text{A}$	---	39	48	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-4\text{A}$	---	53	65	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
			---	5	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{D}}=-6\text{A}$	---	11	---	S

**Dynamic and switching Characteristics**

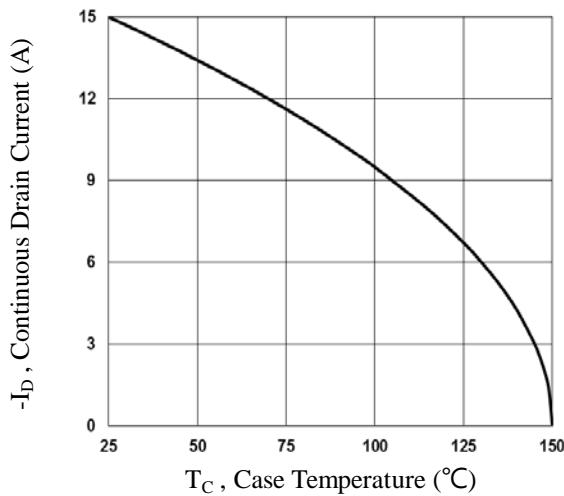
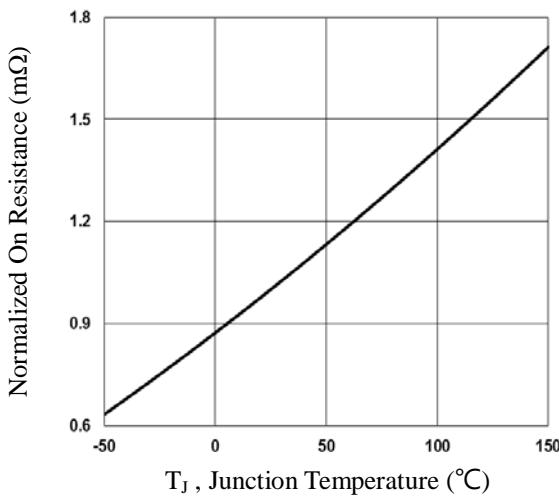
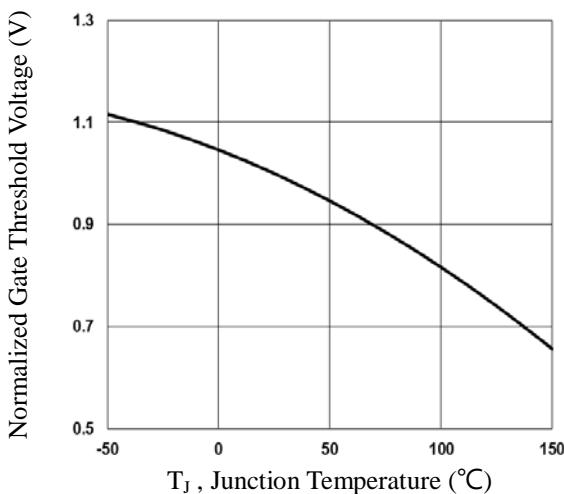
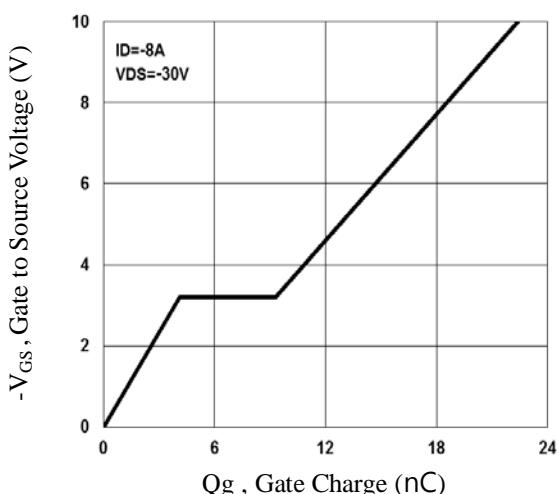
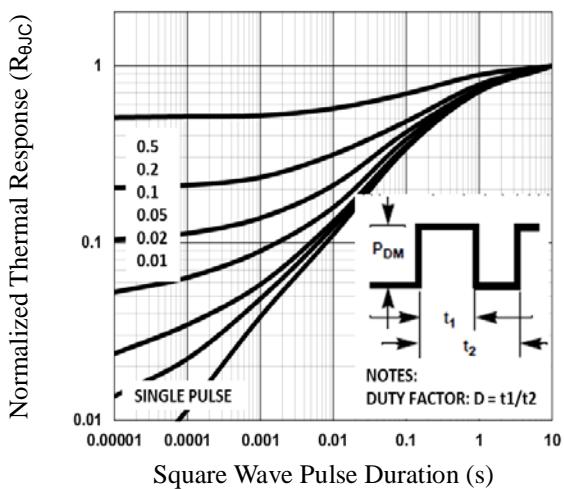
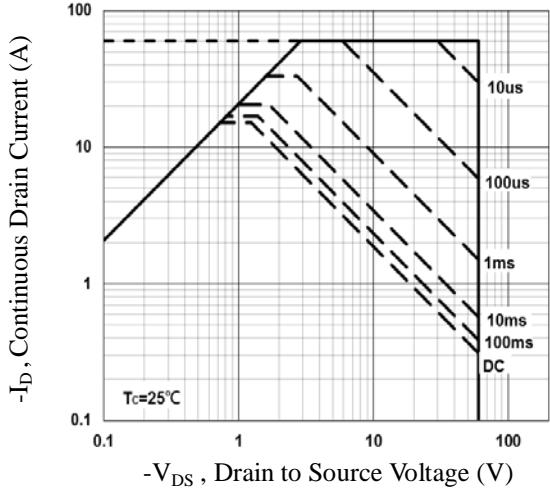
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-8\text{A}$	---	22.4	31	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3,4</sup>		---	4.1	6	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3,4</sup>		---	5.2	8	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3,4</sup>	$V_{\text{DD}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_{\text{G}}=6\Omega$	---	13	25	ns
$T_r$	Rise Time <sup>3,4</sup>		---	42.4	81	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3,4</sup>		---	64.6	123	
$T_f$	Fall Time <sup>3,4</sup>		---	16.4	31	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1250	1810	pF
$C_{\text{oss}}$	Output Capacitance		---	85	125	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	65	95	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	15	30	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-15	A
			---	---	-60	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	---	---	ns
		$T_J=25^\circ\text{C}$	---	---	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=-25\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=-32\text{A}$ ,  $R_{\text{G}}=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1** Continuous Drain Current vs. T<sub>C</sub>

**Fig.2** Normalized RD<sub>ON</sub> vs. T<sub>J</sub>

**Fig.3** Normalized V<sub>th</sub> vs. T<sub>J</sub>

**Fig.4** Gate Charge Waveform

**Fig.5** Normalized Transient Impedance

**Fig.6** Maximum Safe Operation Area

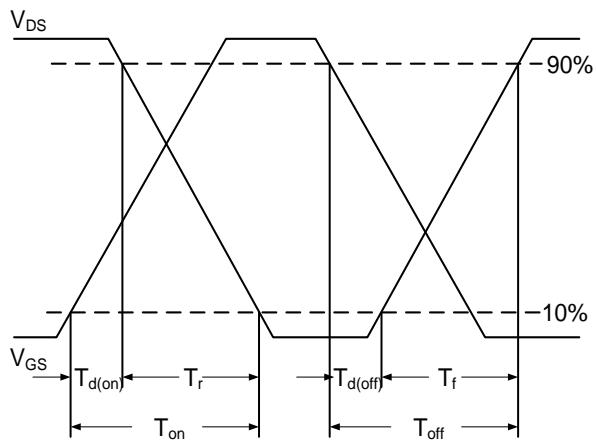


Fig.7 Switching Time Waveform

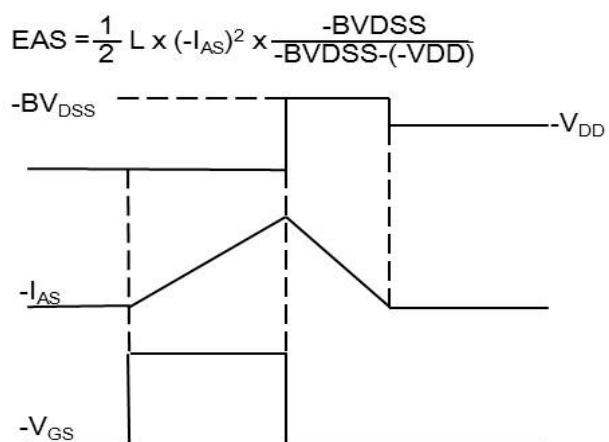
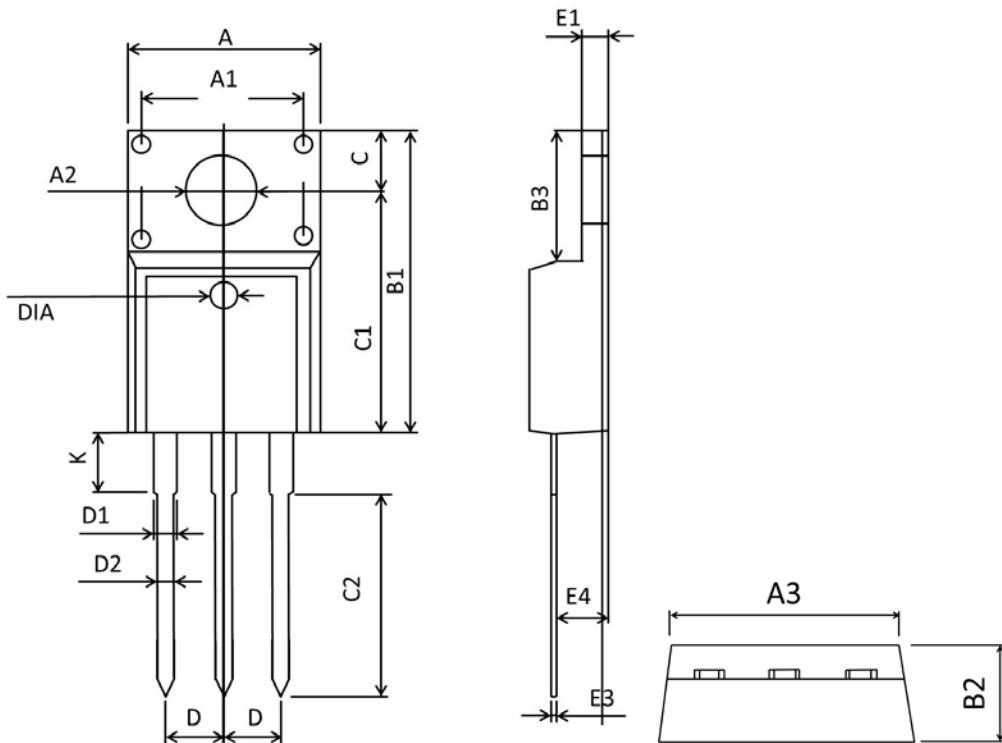


Fig.8 EAS Waveform

## TO220F PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.860	10.460	0.389	0.411
A1	6.900	7.100	0.272	0.279
A2	3.100	3.500	0.123	0.137
B1	9.500	9.900	0.375	0.389
B2	4.500	4.900	0.178	0.192
B3	6.480	6.880	0.256	0.271
C	3.100	3.500	0.123	0.137
C1	12.270	12.870	0.484	0.506
C2	12.580	13.380	0.496	0.526
D	2.490	2.590	0.099	0.101
D1	1.070	1.470	0.043	0.057
D2	0.700	0.900	0.028	0.035
K	2.900	3.300	0.115	0.129
E1	2.340	2.740	0.093	0.107
E3	0.400	0.600	0.016	0.023
E4	2.560	2.960	0.101	0.116
DIA	1.45	1.55	0.058	0.061